



STB80NF55-06 - STB80NF55-06-1 STP80NF55-06 - STP80NF55-06FP

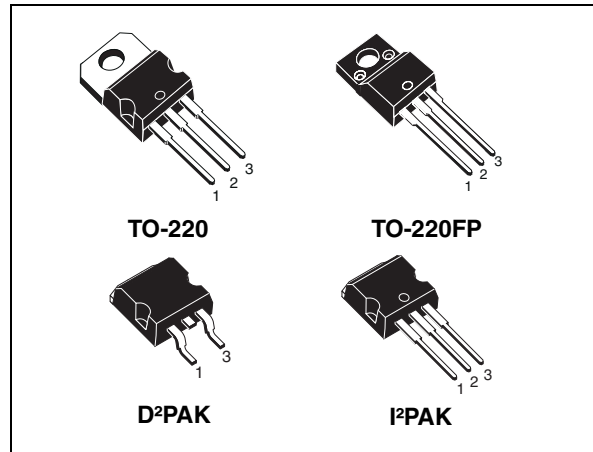
N-channel 55V - 0.005Ω - 80A - TO-220 /FP - I²PAK - D²PAK
STripFET™ II Power MOSFET

General features

Type	V _{DSS} (@T _{Jmax})	R _{DS(on)}	I _D
STB80NF55-06	55V	<0.0065Ω	80A ⁽¹⁾
STB80NF55-06-1	55V	<0.0065Ω	80A ⁽¹⁾
STP80NF55-06	55V	<0.0065Ω	80A ⁽¹⁾
STP80NF55-06FP	55V	<0.0065Ω	60A ⁽¹⁾

1. Limited by package

- Exceptional dv/dt capability
- 100% avalanche tested
- Application oriented characterization



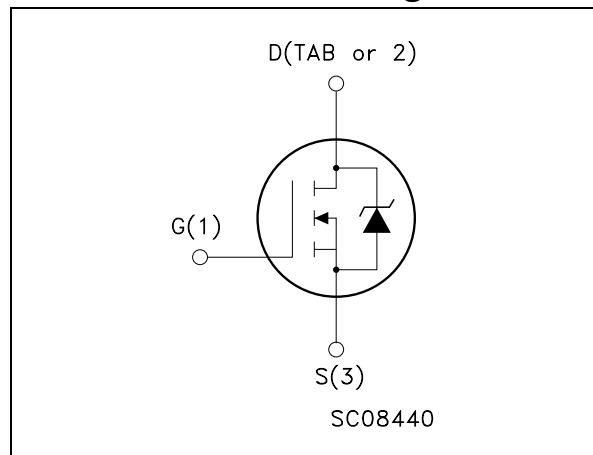
Description

This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

Applications

- Switching application

Internal schematic diagram



Order codes

Part number	Marking	Package	Packaging
STB80NF55-06T4	B80NF55-06	D ² PAK	Tape & reel
STB80NF55-06-1	B80NF55-06	I ² PAK	Tube
STP80NF55-06	P80NF55-06	TO-220	Tube
STP80NF55-06FP	P80NF55-06FP	TO-220FP	Tube

Contents

1 **Electrical ratings** 3

2 **Electrical characteristics** 4

 2.1 Electrical characteristics (curves) 6

3 **Test circuit** 9

4 **Package mechanical data** 10

5 **Packaging mechanical data** 15

6 **Revision history** 16

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		STB80NF55-06 STB80NF55-06-1 STP80NF55-06	STP80NF55-06FP	
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	55		V
V_{DGR}	Drain-gate voltage ($R_{GS} = 20K\Omega$)	55		V
V_{GS}	Gate-source voltage	± 20		V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25^\circ C$	80	60 ⁽²⁾	A
I_D	Drain current (continuous) at $T_C = 100^\circ C$	60	42 ⁽²⁾	A
$I_{DM}^{(3)}$	Drain current (pulsed)	320	240 ⁽²⁾	A
P_{TOT}	Total dissipation at $T_C = 25^\circ C$	300	45	W
	Derating Factor	2	0.30	W/°C
$dv/dt^{(4)}$	Peak diode recovery voltage slope	7		V/ns
$E_{AS}^{(5)}$	Single pulse avalanche energy	1.3		J
V_{ISO}	Insulation withstand voltage (DC)	--	2500	V
T_J T_{stg}	Operating junction temperature Storage temperature	-55 to 175		°C

1. Limited by Package
2. Limited only by maximum temperature allowed
3. Pulse width limited by safe operating area
4.) $I_{SD} \leq 30A$, $di/dt \leq 400A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq T_{JMAX}$
5. Starting $T_J = 25^\circ C$, $I_D = 40A$, $V_{DD} = 45V$

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		TO-247 D ² PAK TO-220	TO-220FP	
R_{thJC}	Thermal resistance junction-case max	0.5	3.33	°C/W
R_{thJA}	Thermal resistance junction-ambient max	62.5		°C/W
T_l	Maximum lead temperature for soldering purpose	300		°C

2 Electrical characteristics

($T_{CASE}=25^{\circ}\text{C}$ unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 250\mu\text{A}$, $V_{GS} = 0$	55			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$, $V_{DS} = \text{Max rating @ } 125^{\circ}\text{C}$			1 10	μA μA
I_{GSS}	Gate body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{V}$, $I_D = 40\text{A}$		0.005	0.0065	Ω

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$g_{fs}^{(1)}$	Forward transconductance	$V_{DS} = 15\text{V}$, $I_D = 40\text{A}$		150		S
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25\text{V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$		4400 1020 350		pF pF pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 44\text{V}$, $I_D = 80\text{A}$ $V_{GS} = 10\text{V}$		142 29 60.5	189	nC nC nC

1. Pulsed: pulse duration=300 μs , duty cycle 1.5%

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 50\text{ V}$, $I_D = 40\text{A}$, $R_G = 4.7\Omega$, $V_{GS} = 10\text{V}$ (see Figure 15)		27		ns
t_r	Rise time			155		ns
$t_{d(off)}$	Turn-off delay time			125		ns
t_f	Fall time			65		ns

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain current				80	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				320	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD}=80A$, $V_{GS}=0$			1.5	V
t_{rr}	Reverse recovery time	$I_{SD}=80A$, $di/dt = 100A/\mu s$, $V_{DD}=35V$, $T_J = 150^{\circ}C$		100		ns
Q_{rr}	Reverse recovery charge			0.32		μC
I_{RRM}	Reverse recovery current			6.5		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration=300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area TO-220

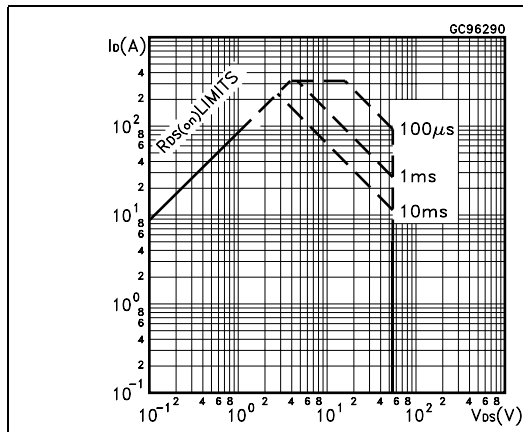


Figure 2. Thermal impedance

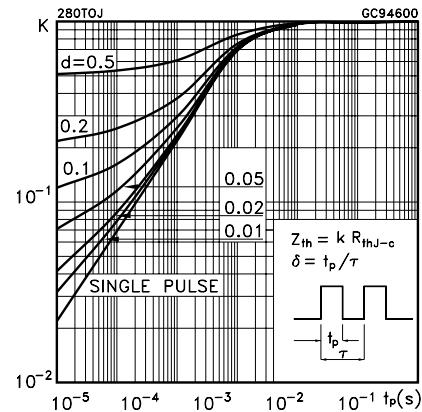


Figure 3. Safe operating area for TO-220FP

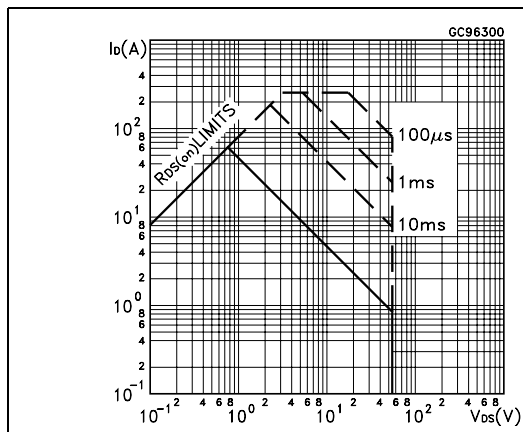


Figure 4. Thermal impedance for TO-220FP

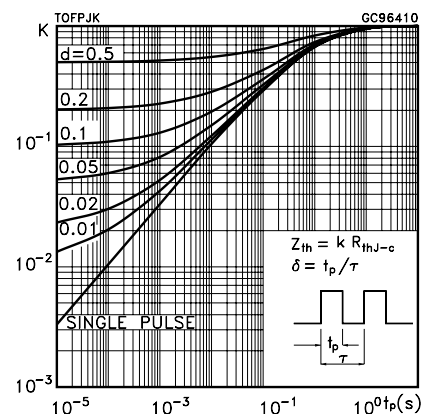


Figure 5. Output characteristics

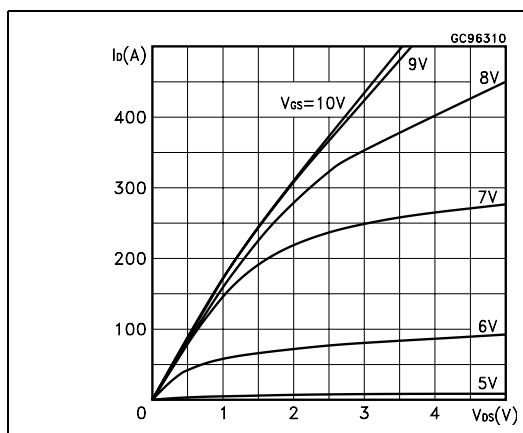


Figure 6. Transfer characteristics

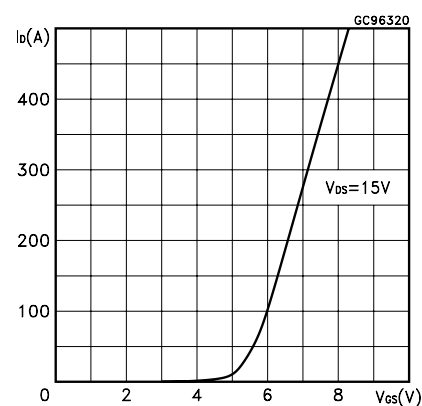


Figure 7. Transconductance

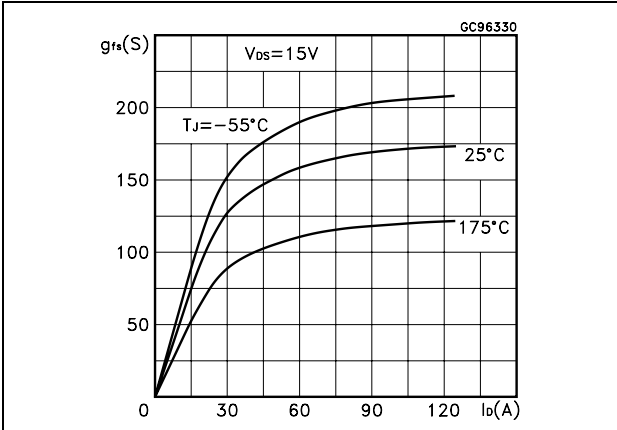


Figure 8. Static drain-source on resistance

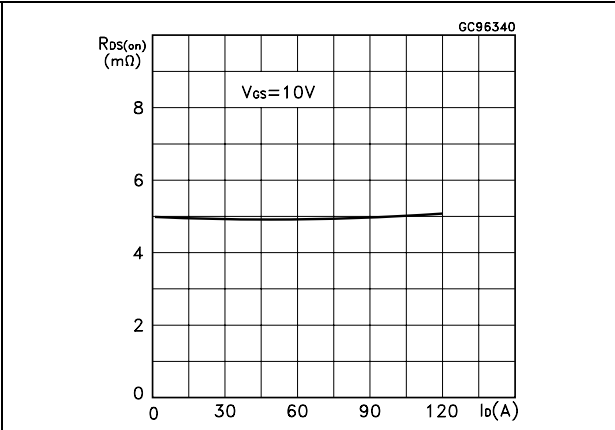


Figure 9. Gate charge vs gate-source voltage Figure 10. Capacitance variations

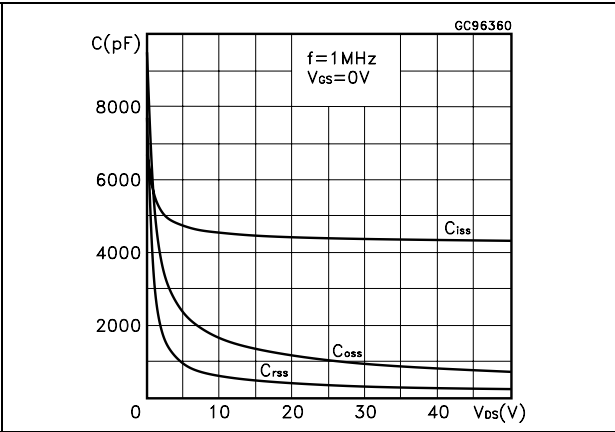
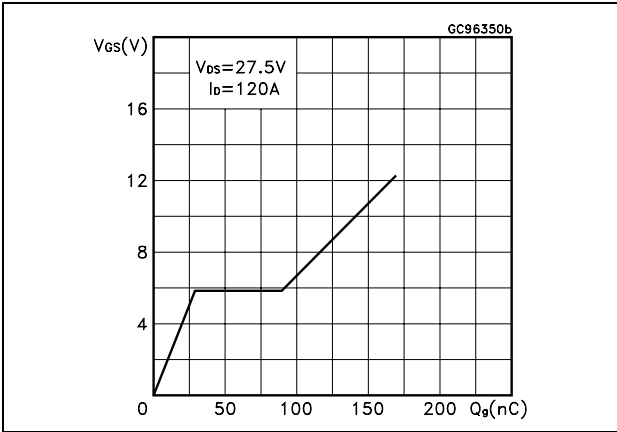


Figure 11. Normalized gate threshold voltage vs temperature

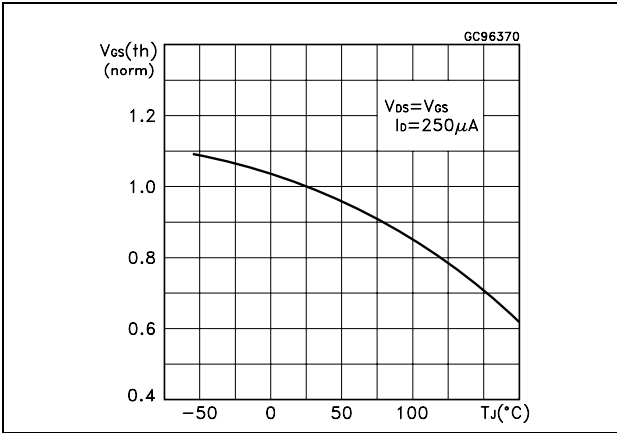


Figure 12. Normalized on resistance vs temperature

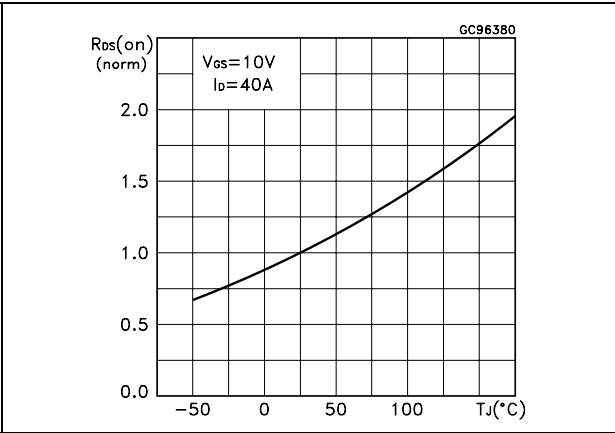


Figure 13. Source-drain diode forward characteristics

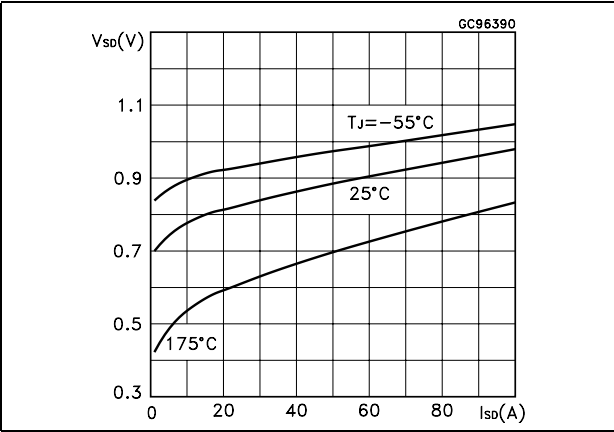
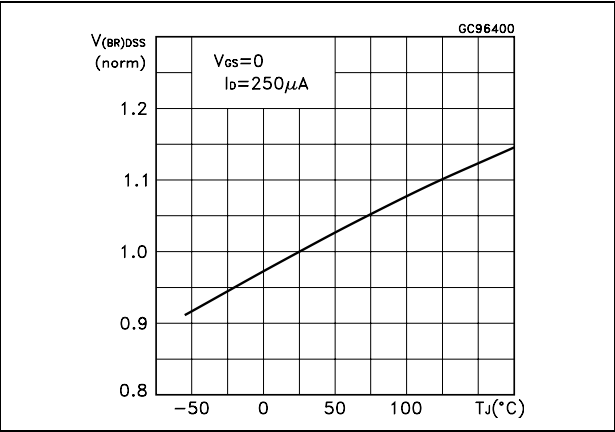


Figure 14. Normalized B_{VDSS} vs temperature



3 Test circuit

Figure 15. Switching times test circuit for resistive load

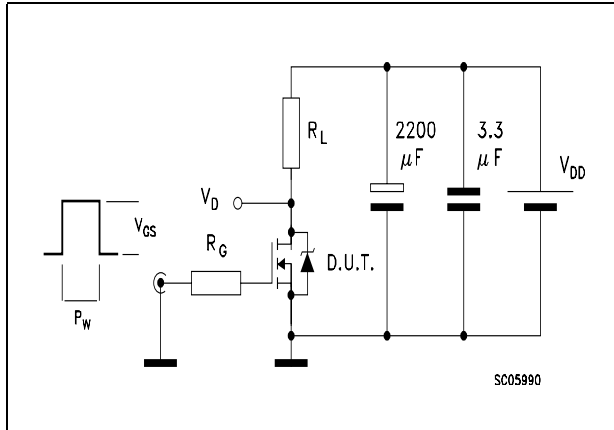


Figure 16. Gate charge test circuit

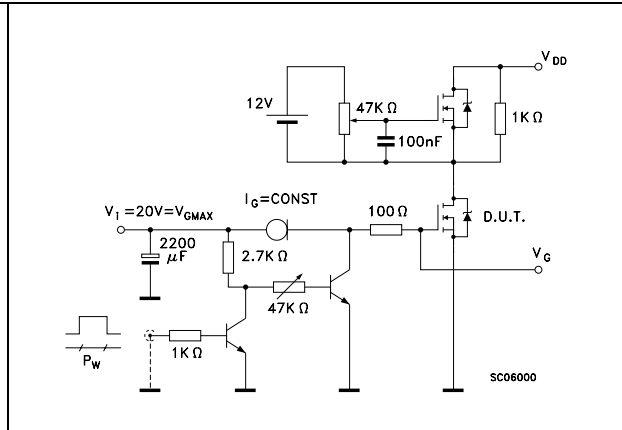


Figure 17. Test circuit for inductive load switching and diode recovery times

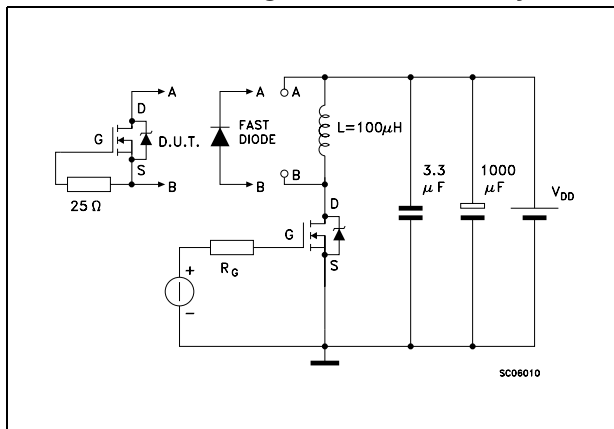


Figure 18. Unclamped Inductive load test circuit

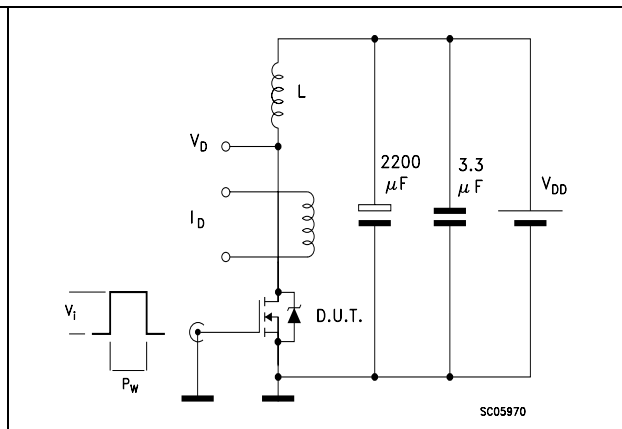
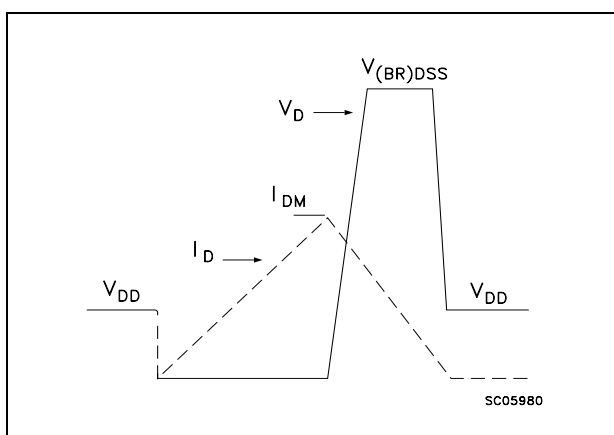


Figure 19. Unclamped inductive waveform

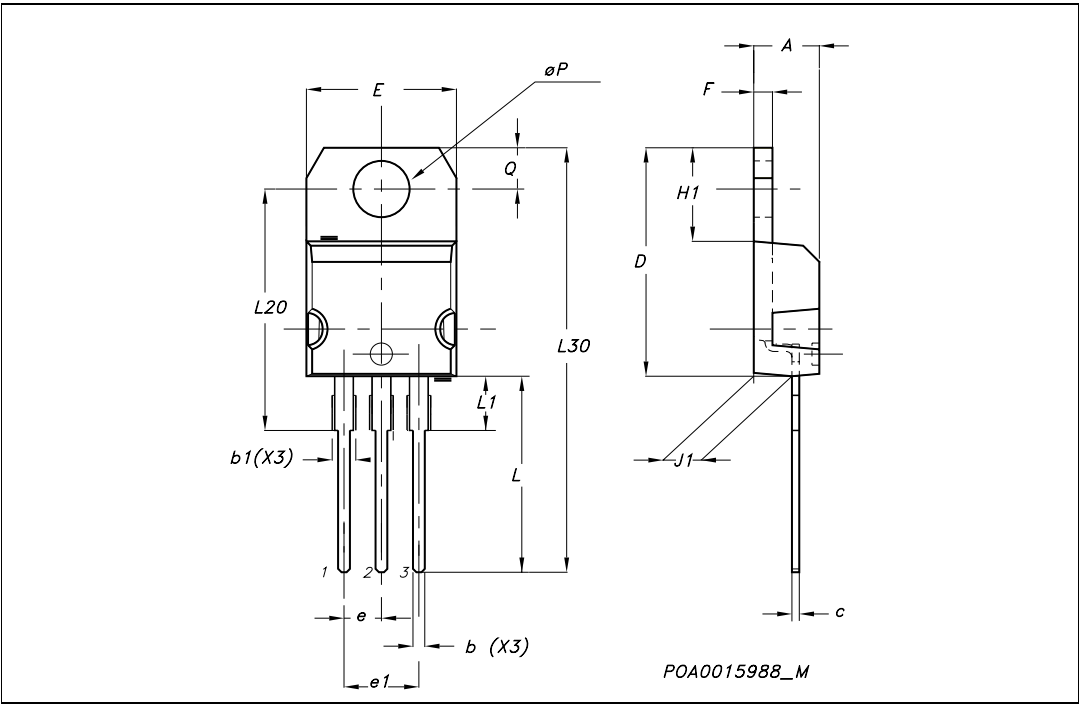


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

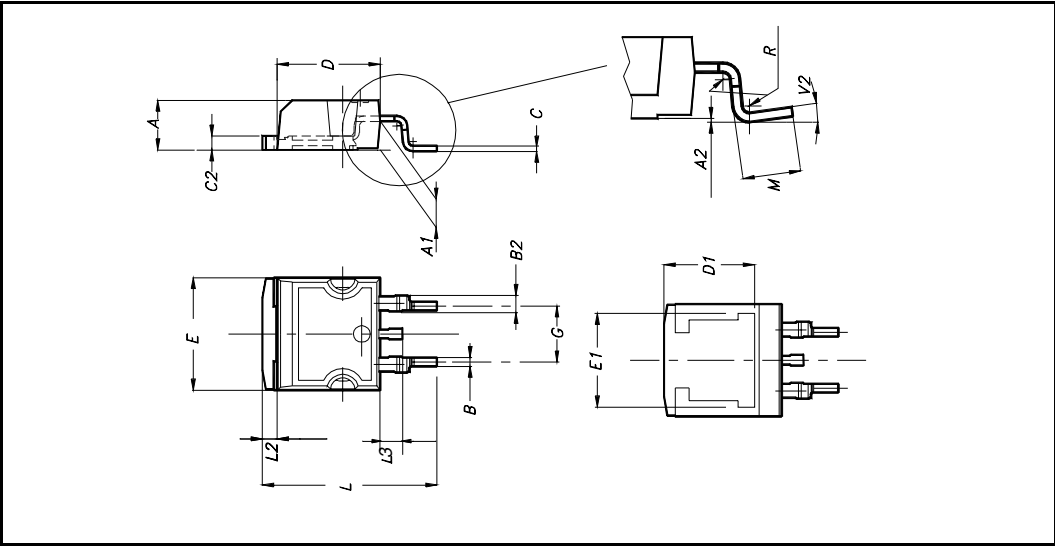
TO-220 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



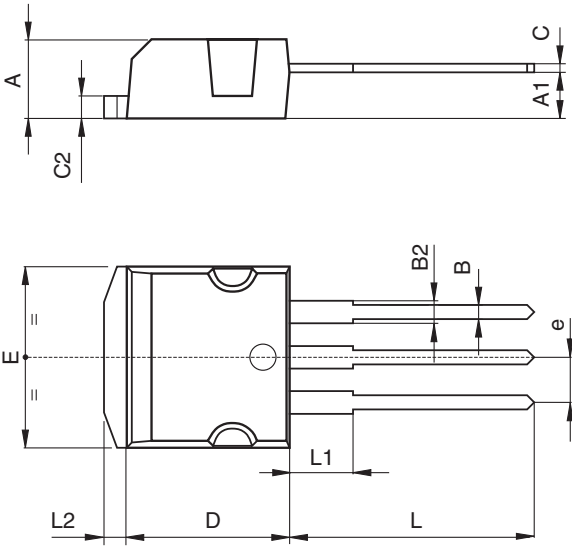
D²PAK MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
D1		8			0.315	
E	10		10.4	0.393		
E1		8.5			0.334	
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.625
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068
M	2.4		3.2	0.094		0.126
R		0.4			0.015	
V2	0°		4°			



TO-262 (I²PAK) MECHANICAL DATA

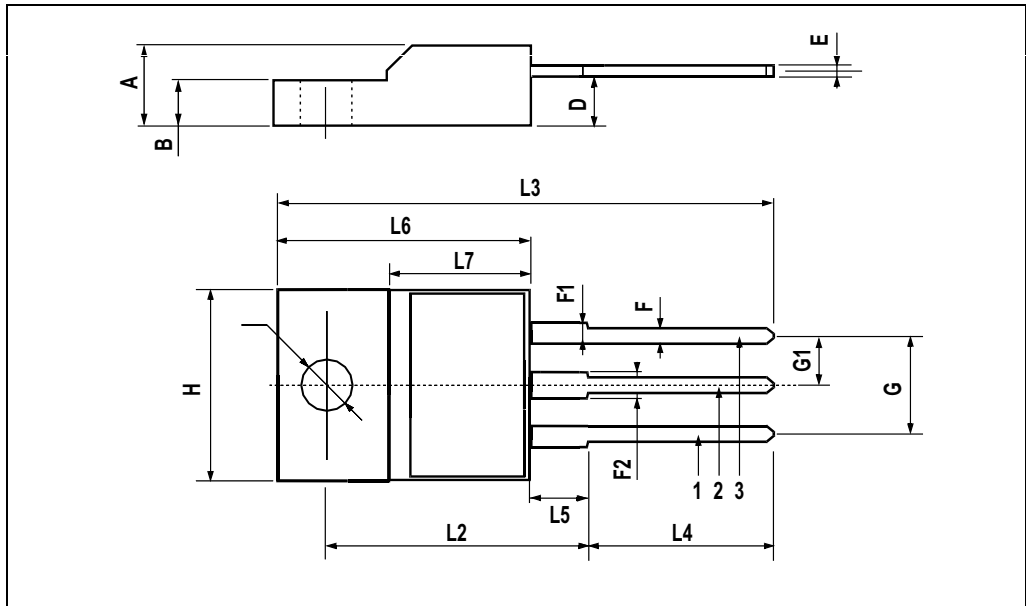
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
A1	2.49		2.69	0.098		0.106
B	0.7		0.93	0.027		0.036
B2	1.14		1.7	0.044		0.067
C	0.45		0.6	0.017		0.023
C2	1.23		1.36	0.048		0.053
D	8.95		9.35	0.352		0.368
e	2.4		2.7	0.094		0.106
E	10		10.4	0.393		0.409
L	13.1		13.6	0.515		0.531
L1	3.48		3.78	0.137		0.149
L2	1.27		1.4	0.050		0.055



P011P5/E

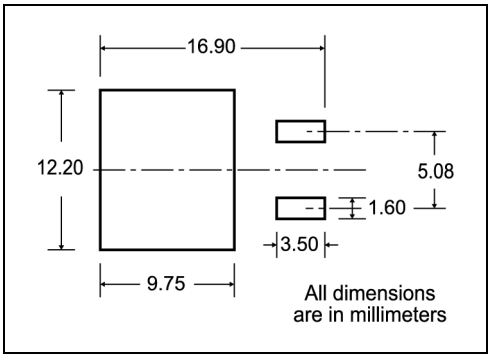
TO-220FP MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126

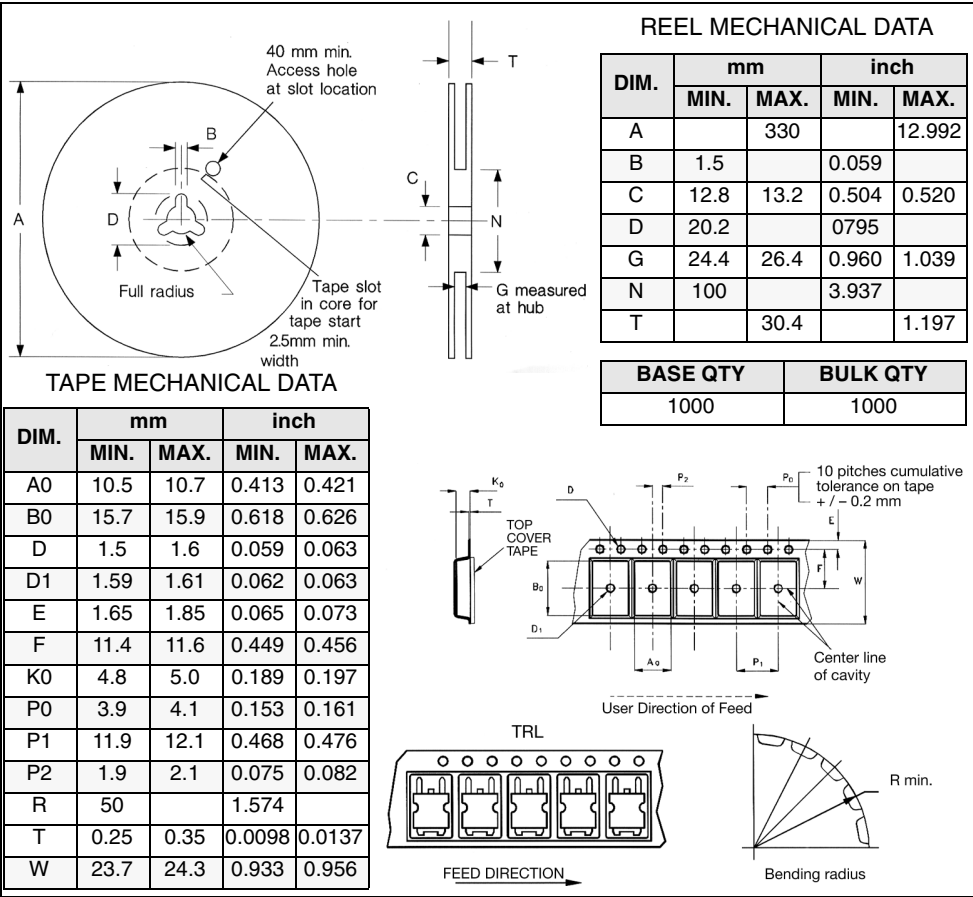


5 Packaging mechanical data

D²PAK FOOTPRINT



TAPE AND REEL SHIPMENT



* on sales type

6 Revision history

Table 7. Revision history

Date	Revision	Changes
21-Jun-2004	5	Complete version
13-Mar-2005	6	Package inserted: I ² PAK
20-Jul-2006	7	New template, no content change

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